

KEK Beam Test Updates

2026/1/13

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- For the upcoming beam test

Beam Test

- Dec. 1- 10, 2025 @ KEK
 - Using electron beams (1-5 GeV)
 - Validated daisy-chained multi-chip operation under beam conditions
 - Three-layer of v3 quad-chips
 - enabled the definition of coincident events using FPGA timestamps, providing the basis for scaling to large systems with synchronization among and AstroPix layers and between calorimeter and AstroPix layers
 - V4 single chip
 - established critical performance benchmarks for the upcoming v5 sensor.
- Upcoming Beam Test
 - HalD (low energy) by ANL: 2026 March 13 (w1, w2)
 - Run with HGCROC and A-STEP under beam conditions to study the synchronization of two different readouts
 - Run with RCDAQ by Martin
 - KEK by KoBIC
 - HalD (high energy) by ANL : 2026 August 17 (w22, w23)
 - CERN by KoBIC

Beam Test Data Summary

- Assigned beam time for AstroPix ☺: 10 AM, 2025. 12. 9 ~ 5 AM, 2025. 12. 10 (17 hours)
- V3 quad-chip (w112q06)
 - Using parasite beam (4 GeV electron beam; downstream of ITS)
- Three V3 quad-chip stacks (w112q06/w101q04/**w101q12**) ***chip0 of w101q12 is malfunctional.**
 - Using parasite beam (4 GeV electron beam; downstream of ITS)
 - 1 GeV electron beam(~1 kHz): 1 hour 30 mins data-taking ~ Total 5M hits
 - 2 GeV electron beam(2.3-2.4 kHz): 40 mins data-taking ~ Total 5M hits
 - 3 GeV electron beam (1.6-1.7 kHz): 40 mins data-taking ~ Total 5M hits
 - 4 GeV electron beam (~1 kHz): 1 hour 30 mins data-taking ~ Total 6M hits
 - 5 GeV electron beam (~400 Hz): 2 hours data-taking ~ Total 4M hits
- Three V3 quad-chip stacks + two W plates
 - Max buffer. Impossible to save data
- Three V3 quad-chip stacks + one W plate (5 mm thickness = 1 radiation length)
 - W plate Between layer2 and layer3 (w112q06/w101q04/[W plate]/ **w101q12**)
 - 5 GeV electron beam (438 Hz): 10 mins data-taking
 - W plate Between layer1 and layer2 (w112q06/[W plate]/ w101q04/ **w101q12**)
 - 5 GeV electron beam (438 Hz): 10 mins data-taking
 - W plate Between layer1 and layer2 (w112q06/[W plate]/ **w101q12**/w101q04)
 - 5 GeV electron beam (438 Hz): 1 hour data-taking
 - 1 GeV electron beam (1.1-1.2 kHz): 30 mins data-taking
- V4 single chip
 - 3 GeV electron beam (1.6-1.7 kHz)

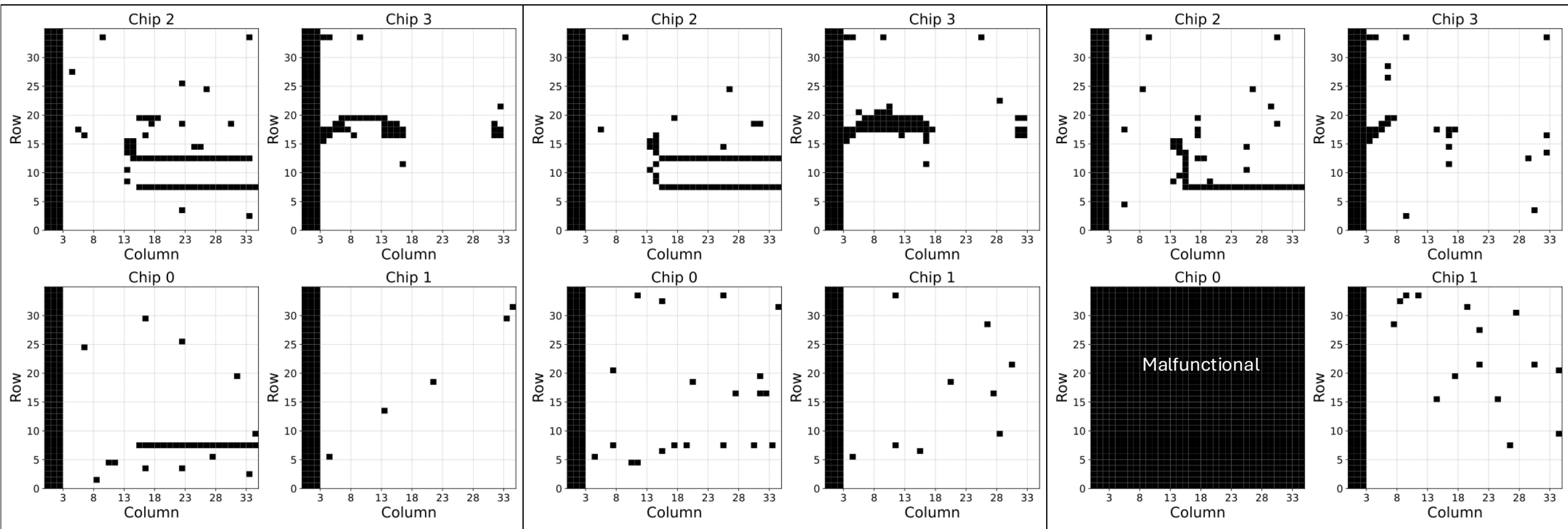
*During data-taking: 540 mA @5.3V

→ Define one event using FPGA timestamp for synchronization

Mask maps: w112q06/w101q04/w101q12

- Active pixel yield (#. masked pixels)

*Regardless of whether the pixel was enabled or disabled, there was no response on chip0 of w101q12.



| | | | |
|--------|--------------|--------|--------------|
| Chip 2 | 86.0 % (172) | Chip 3 | 88.2 % (145) |
| Chip 0 | 88.8 % (137) | Chip 1 | 91.0 % (110) |

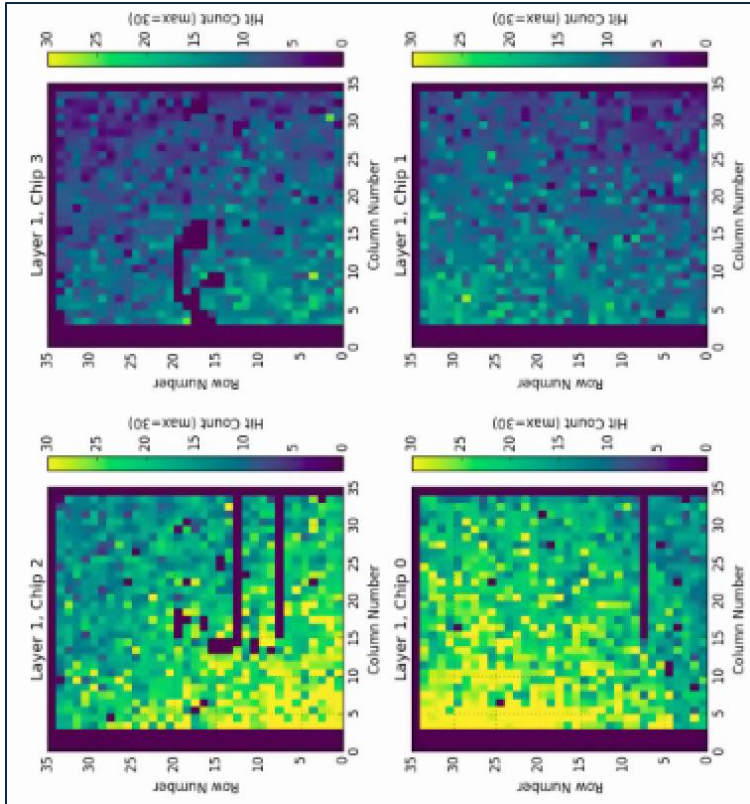
| | | | |
|--------|--------------|--------|--------------|
| Chip 2 | 86.8 % (162) | Chip 3 | 86.5 % (165) |
| Chip 0 | 89.8 % (125) | Chip 1 | 90.7 % (114) |

| | | | |
|--------|--------------|--------|--------------|
| Chip 2 | 87.4 % (154) | Chip 3 | 89.2 % (132) |
| Chip 0 | 0 (1225) | Chip 1 | 90.2 % (120) |

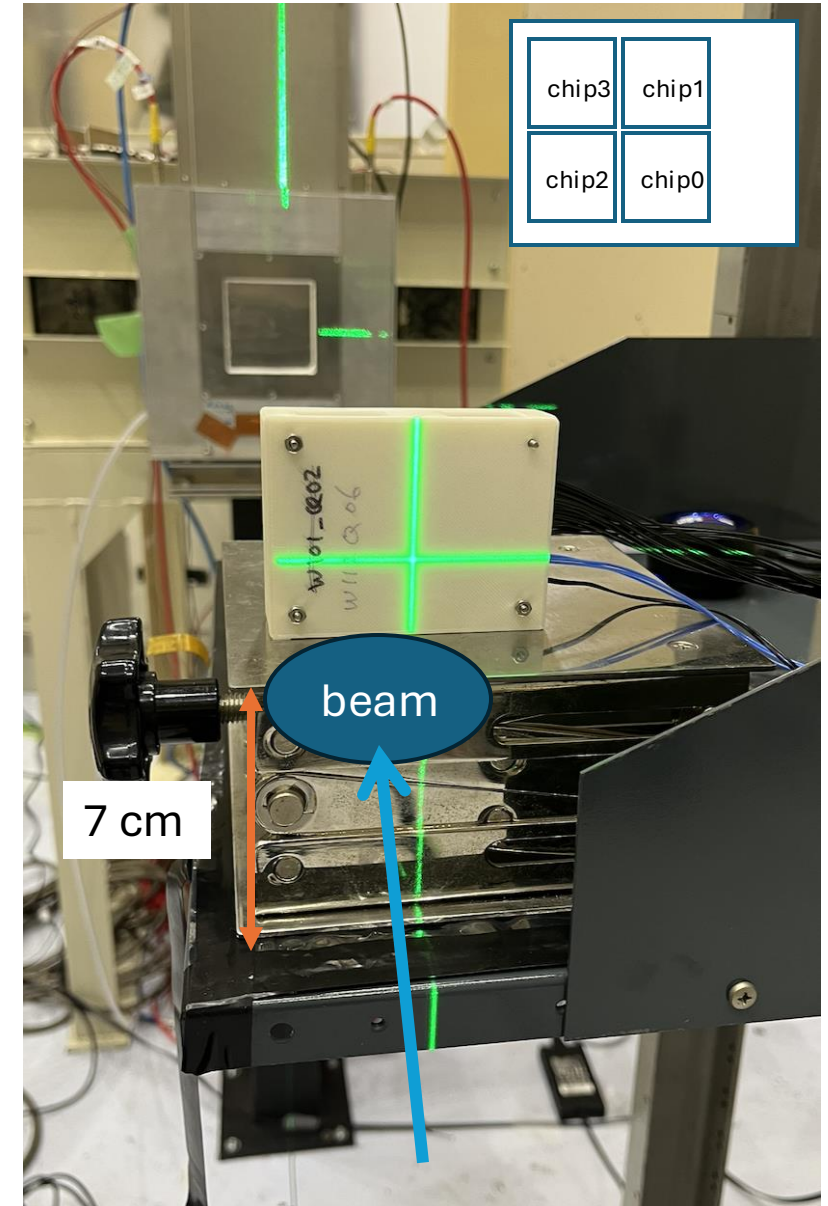
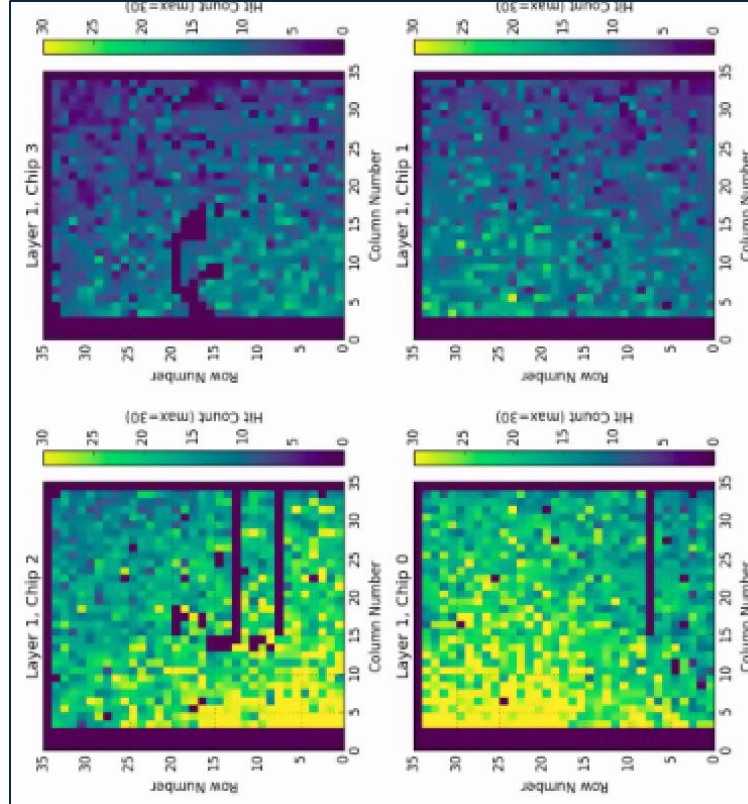
v3 Quad chips: Beam Test Setup

- Parasite beam; 3.5m behind from ITS setup
- 1st v3 quad-chip (w112q06) response under beam environment
- Move vertically and horizontally the beam center

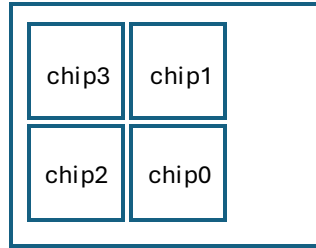
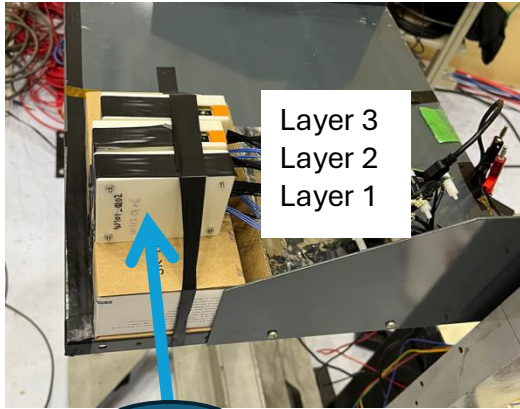
152304 (5 mins run)



153305 (5 mins run)



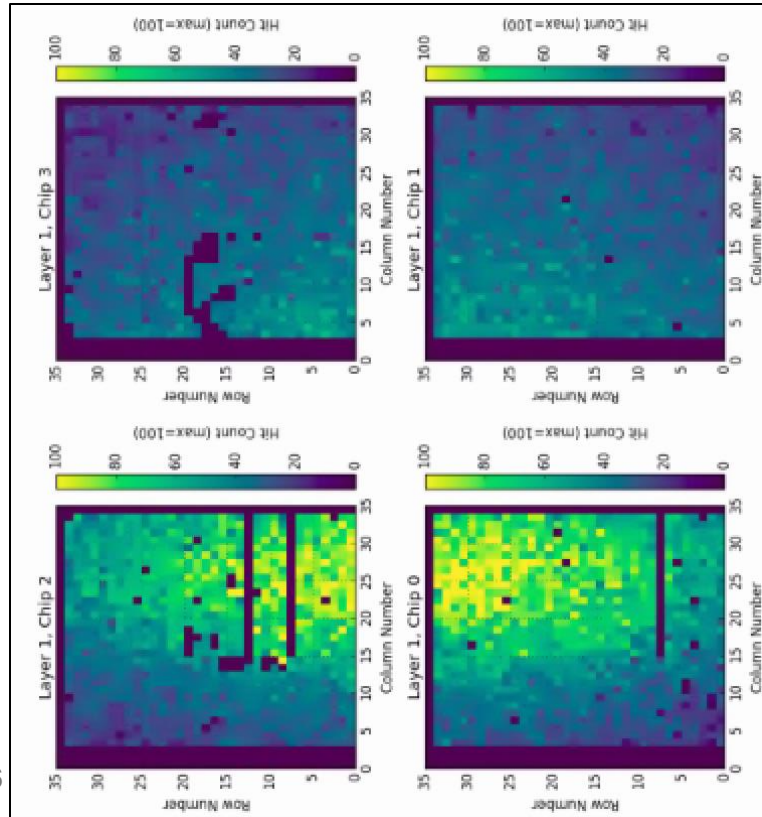
Three v3 Quad chips: Beam Test Setup



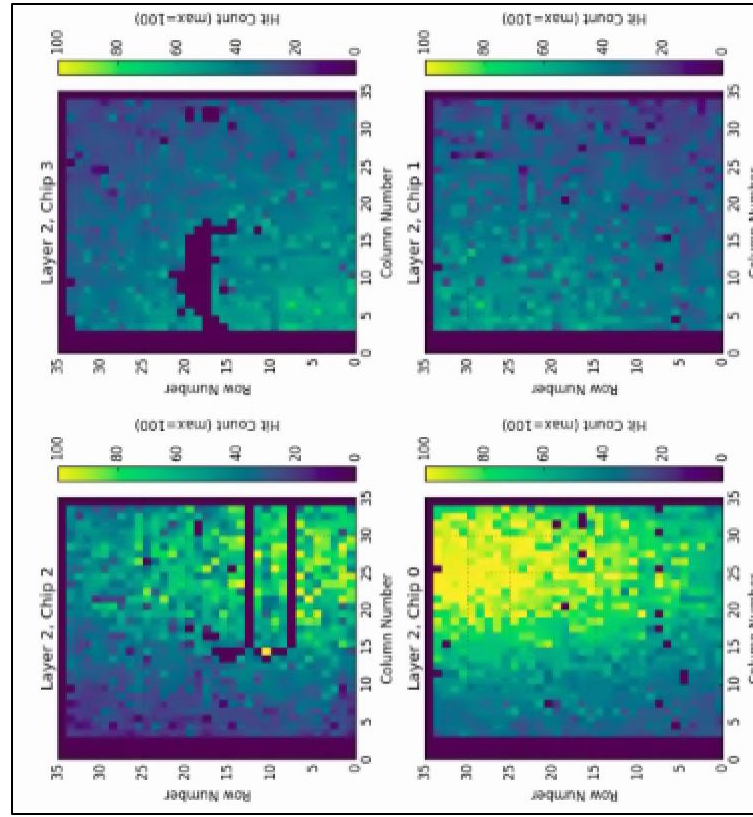
- Parasite beam; 3.5m behind from ITS setup
 - 4 GeV electron beam
- 1st three v3 quad-chip stacks response under beam environment
- Data-taking rate < 600 (/4096 Max buffer)

beam

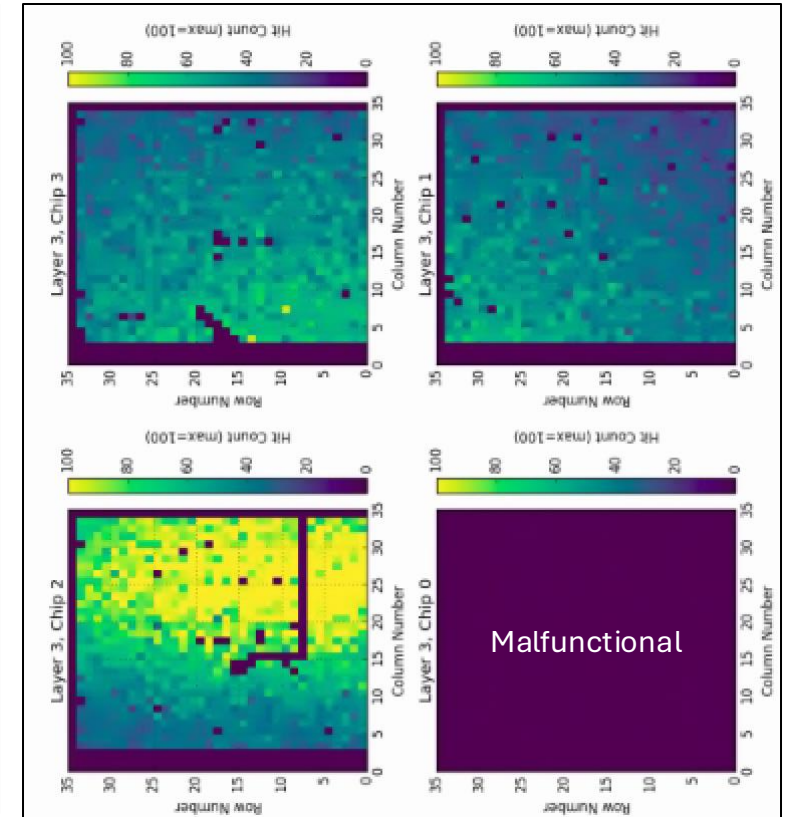
Layer 1 (w112q06)



Layer 2 (w101q04)

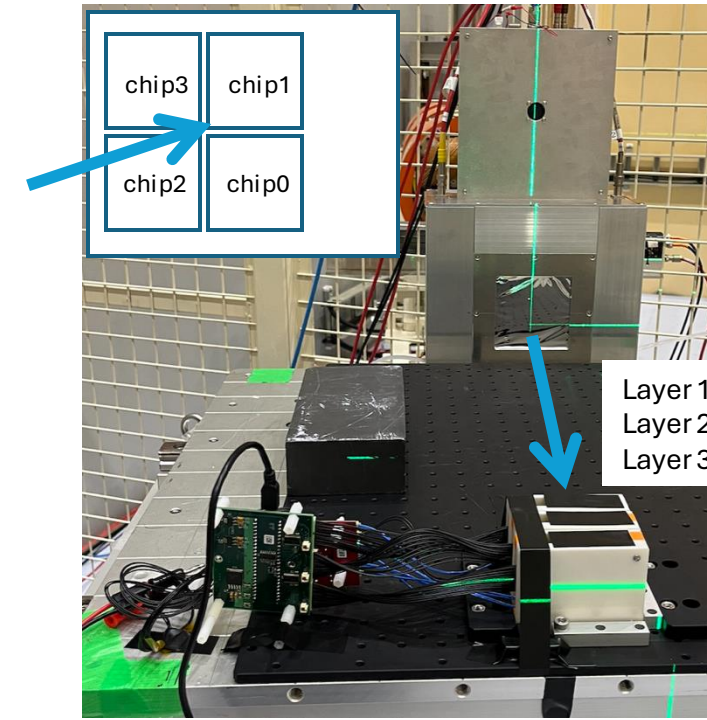


Layer 3 (w101q12)

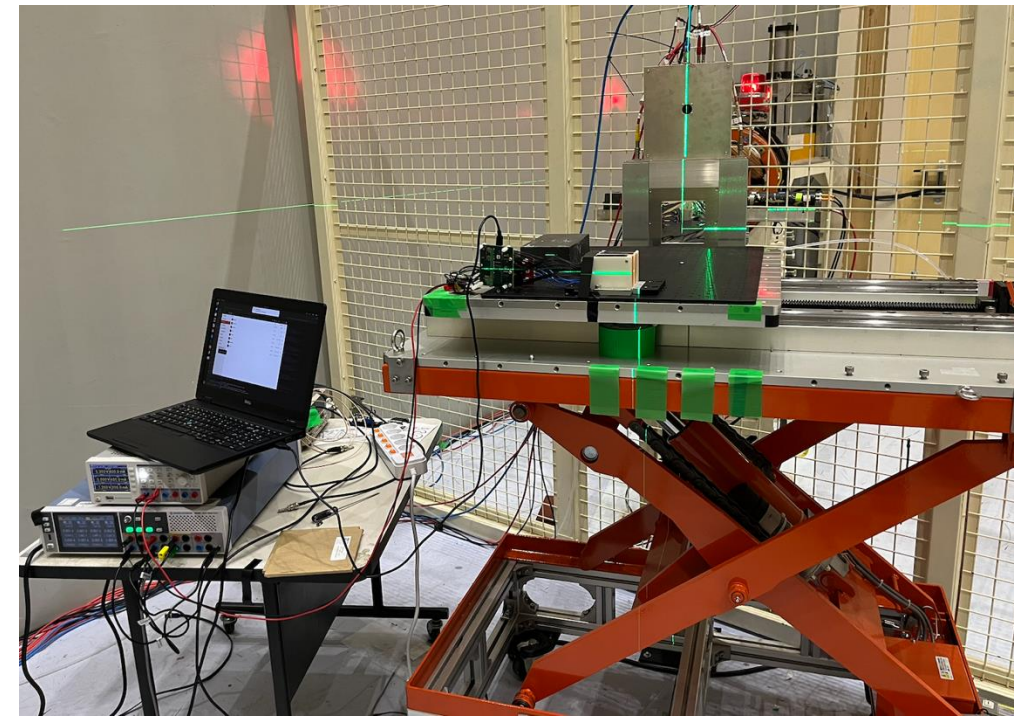
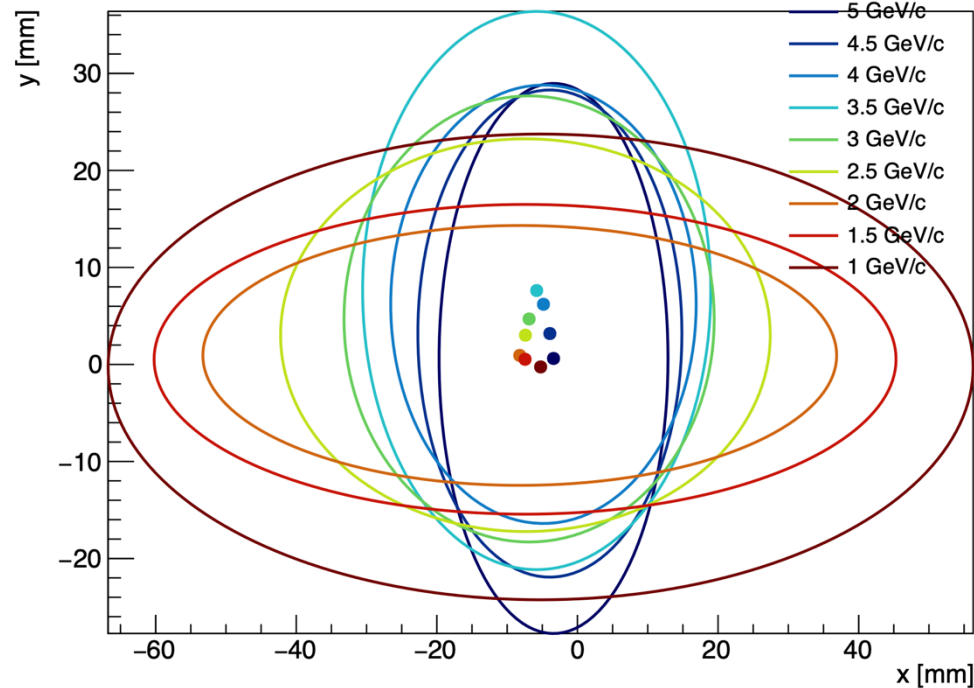


Three v3 Quad chips: Beam Test Setup

- 1st three v3 quad-chips stack response under beam environment
- 1, 2, 3, 4, and 5 GeV electron beams → Stable data-taking



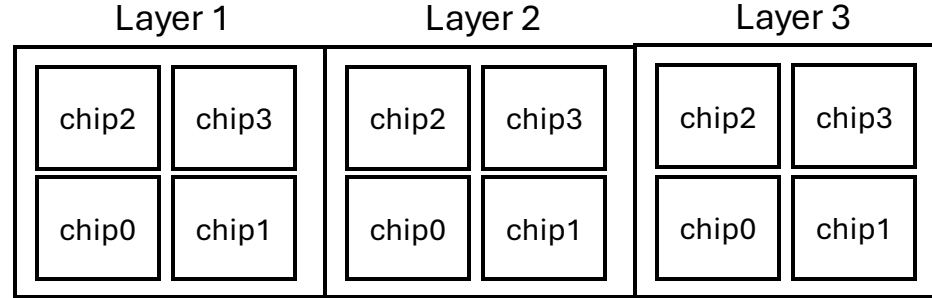
Beam profile with beam energy change



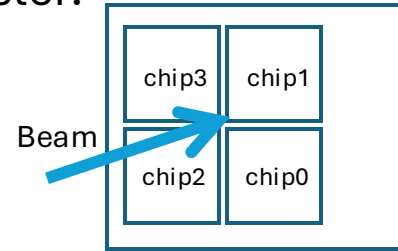
Hit Map & ToT Distribution (1/2 GeV electron beams)

Beam profile with beam energy change

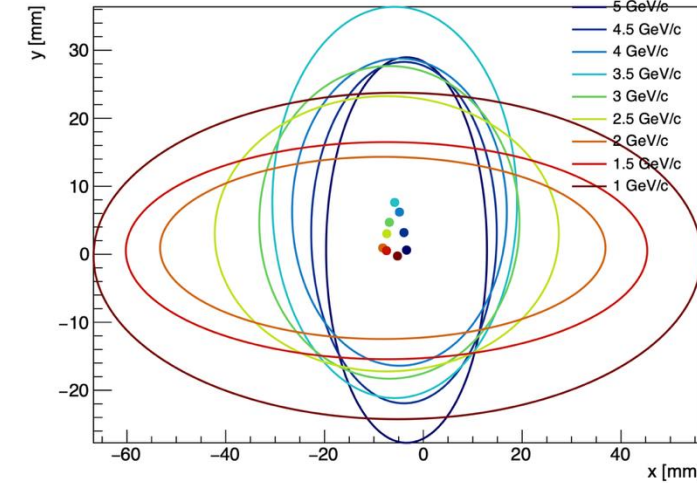
Plot:



Detector:

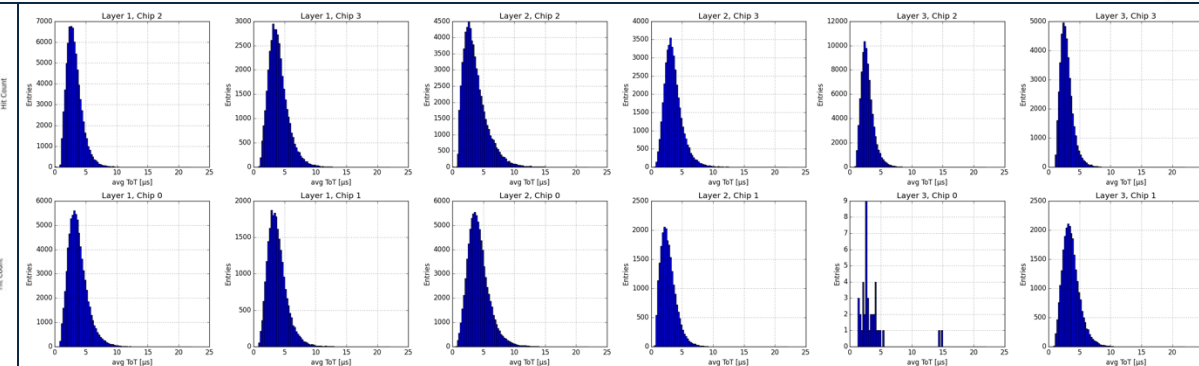
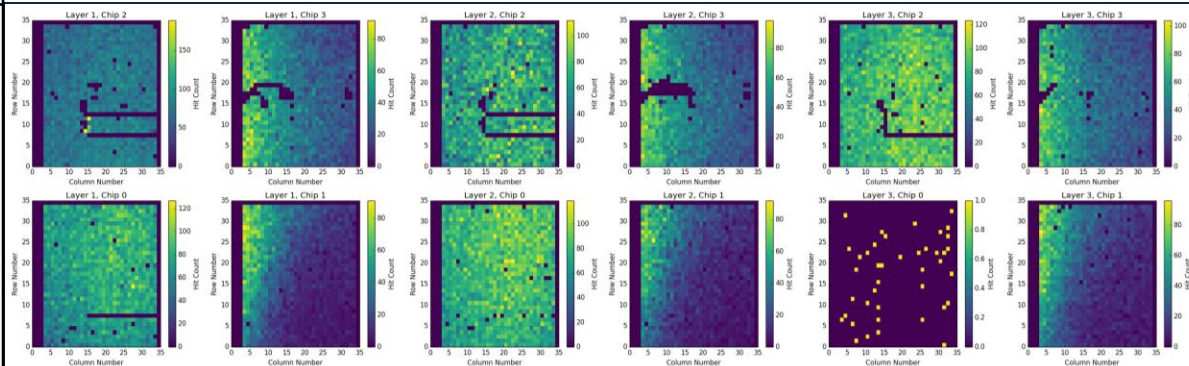


*The hit map matches the actual geometry when rotated 90° counterclockwise.

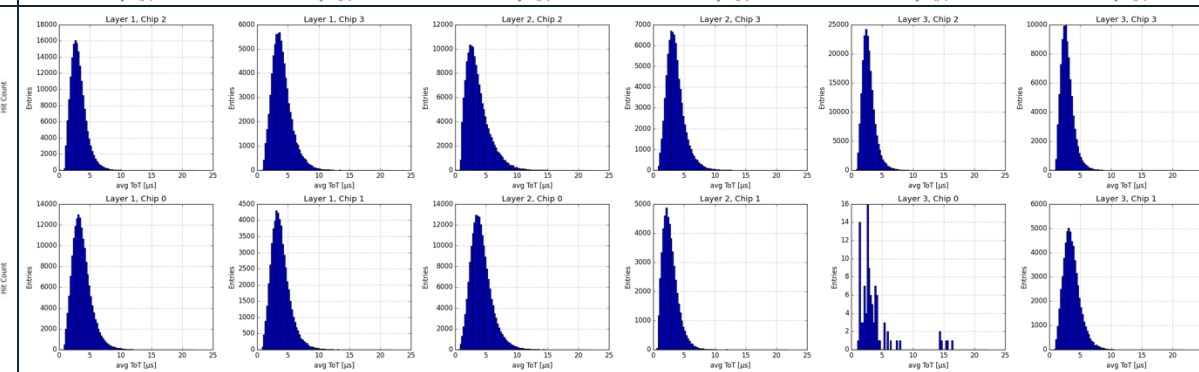
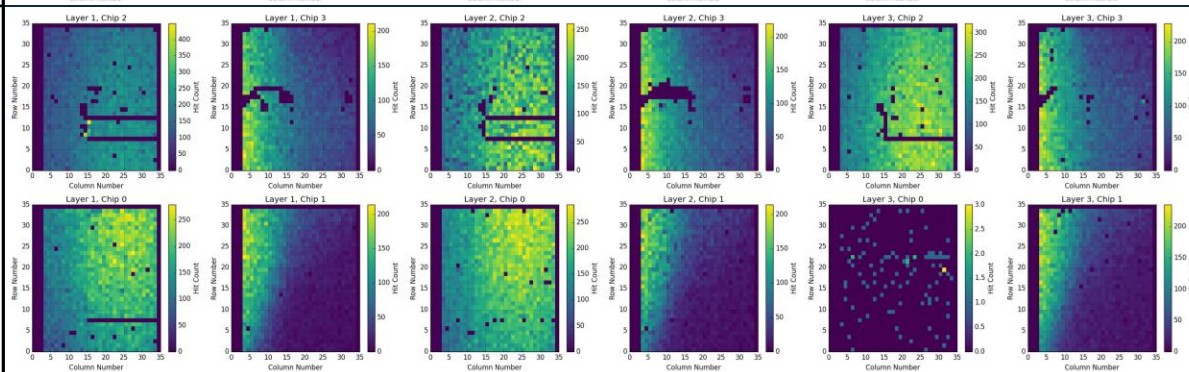


Energy
(Beam
Rate)

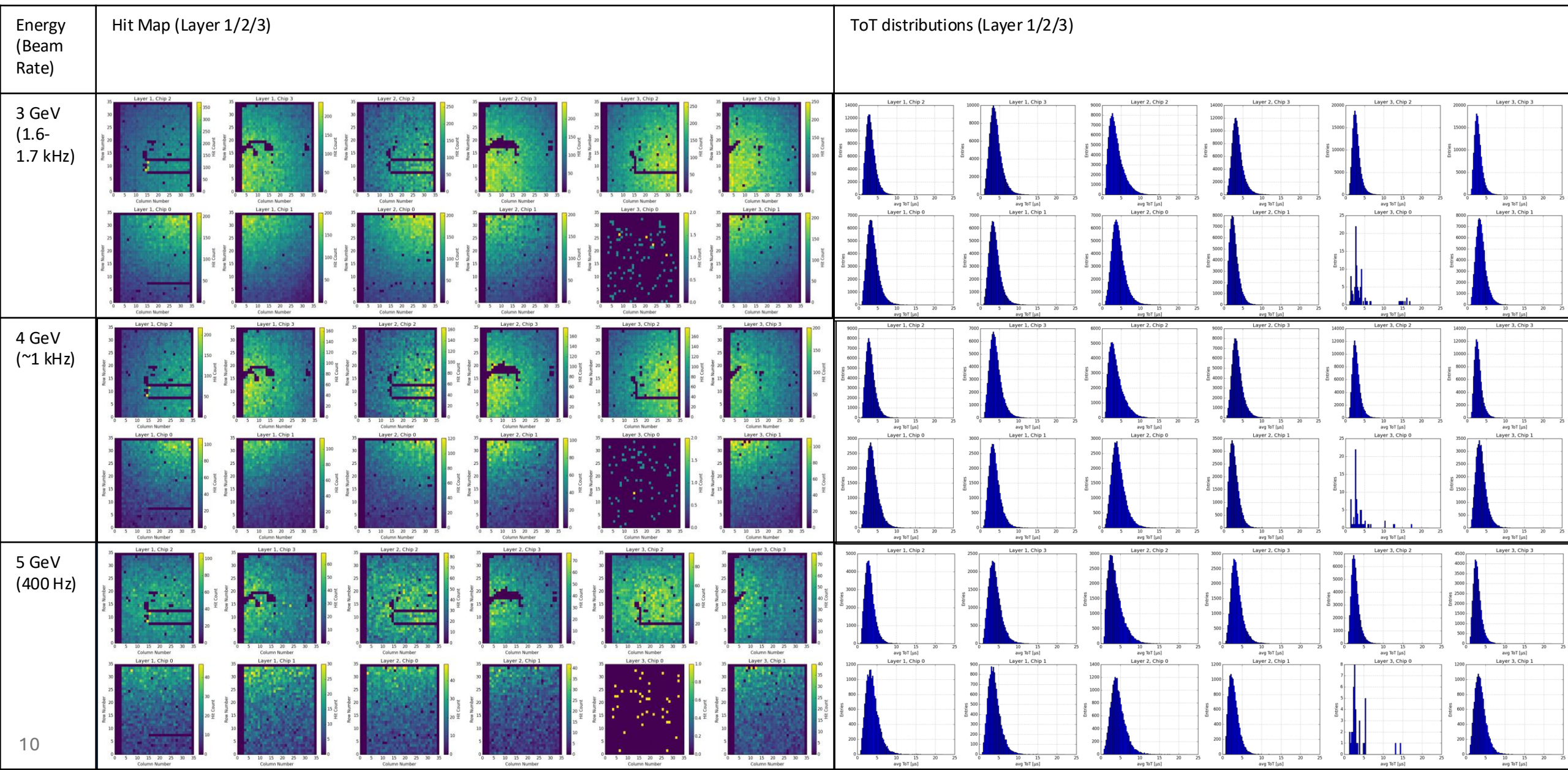
1 GeV
(1.1 kHz)



2 GeV
(2.3
-2.4 kHz)



Hit Map & ToT Distribution (3/4/5 GeV electron beams)

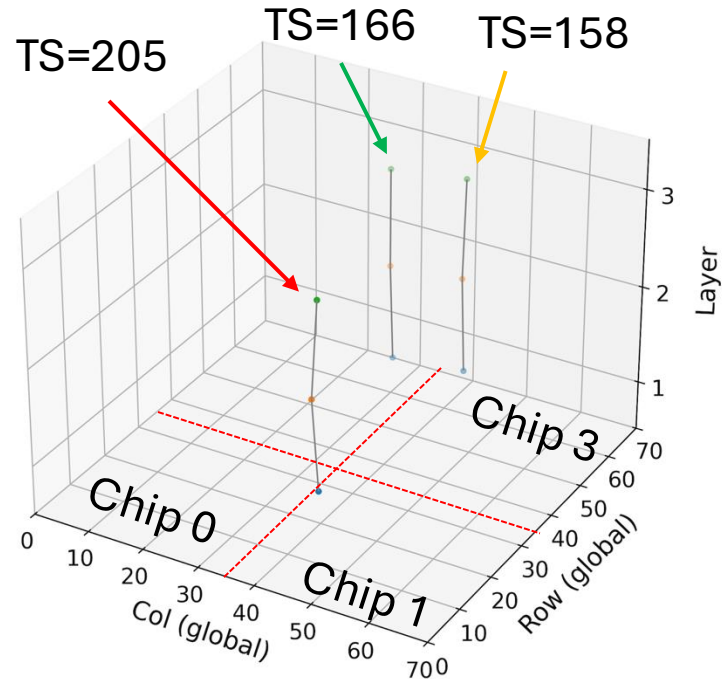


Quick check

- Cut applied: require a common timestamp_col across Layers 1–3 (3-layer coincidence)

| | 1 | Readout | layer | chipID | col | row | timestamp_col | timestamp_row | tot_us_col | tot_us_row | avg_tot_us | fpga_ts_col | fpga_ts_row |
|----|---|---------|-------|--------|-----|-----|---------------|---------------|------------|--------------------|--------------|-------------|-------------|
| 2 | 0 | 3 | 2 | 32 | 10 | 217 | 217 | 1.035 | 1.125 | 1.08 | 2561612459 | 2561612417 | |
| 3 | 0 | 1 | 3 | 16 | 12 | 216 | 216 | 5.175 | 5.29 | 5.2325 | 2561612604 | 2561612478 | |
| 4 | 0 | 2 | 3 | 11 | 10 | 219 | 219 | 2.615 | 2.69 | 2.6525 | 2561612608 | 2561612440 | |
| 5 | 0 | 1 | 3 | 32 | 13 | 216 | 216 | 8.845 | 8.945 | 8.895 | 2561612730 | 2561612520 | |
| 6 | 0 | 2 | 3 | 16 | 12 | 216 | 216 | 5.325 | 5.42 | 5.3725 | 000000000005 | 2561612776 | 2561612524 |
| 7 | 0 | 2 | 3 | 17 | 11 | 217 | 217 | 1.895 | 2.035 | 1.965 | 2561612818 | 2561612482 | |
| 8 | 0 | 2 | 3 | 32 | 13 | 216 | 216 | 11.385 | 11.455 | 11.42 | 2561612902 | 2561612566 | |
| 9 | 0 | 3 | 3 | 14 | 25 | 219 | 219 | 3.61 | 3.72 | 3.665 | 2561634765 | 2561634723 | |
| 10 | 0 | 1 | 3 | 3 | 23 | 219 | 219 | 4.69 | 4.795 | 4.7425 | 2561634771 | 2561634729 | |
| 11 | 0 | 2 | 2 | 5 | 24 | 249 | 249 | 3.63 | 3.695 | 3.6624999999999996 | 2561644904 | 2561644862 | |
| 12 | 0 | 1 | 2 | 11 | 20 | 127 | 127 | 4.605 | 4.71 | 4.6575 | 000000000001 | 2561654513 | 2561654471 |
| 13 | 0 | 1 | 2 | 21 | 15 | 179 | 179 | 3.47 | 3.575 | 3.5225 | 2561666826 | 2561666784 | |
| 14 | 0 | 2 | 2 | 8 | 24 | 32 | 32 | 1.345 | 1.42 | 1.3824999999999998 | 2561766719 | 2561766677 | |
| 15 | 0 | 1 | 2 | 9 | 24 | 31 | 31 | 3.585 | 3.675 | 3.63 | 2561766731 | 2561766689 | |

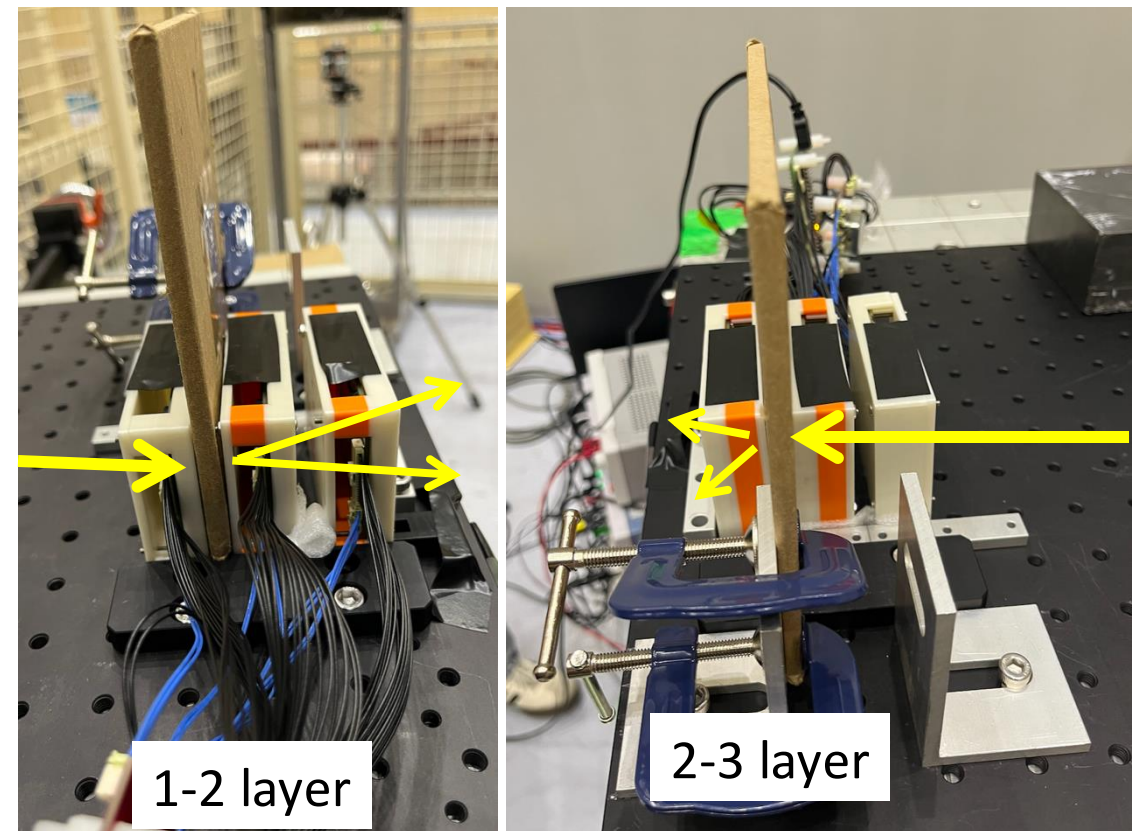
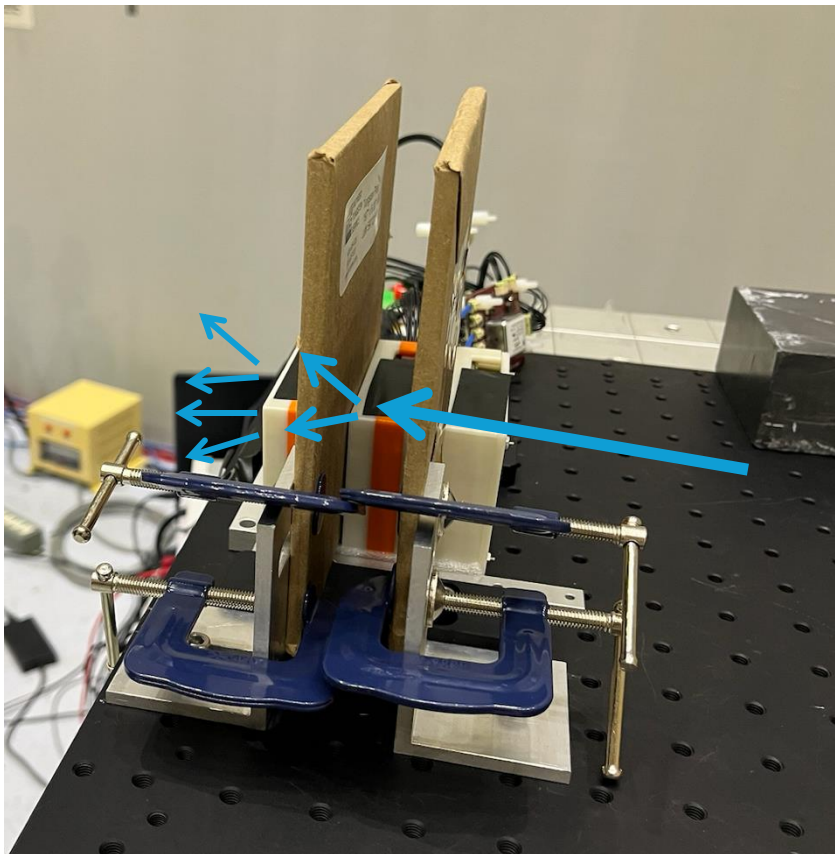
Readout 38, common TS count=3



| | | | | | | | | | | | | | |
|-----|----|---|---|----|----|-----|-----|-------|-------|--------------------|--------------|------------|------------|
| 420 | 38 | 2 | 3 | 3 | 5 | 76 | 76 | 2.42 | 2.505 | 2.4625 | 2570329353 | 2570329311 | |
| 421 | 38 | 2 | 1 | 7 | 14 | 205 | 205 | 1.845 | 1.93 | 1.8875 | 2570371172 | 2570371130 | |
| 422 | 38 | 3 | 1 | 8 | 14 | 205 | 205 | 3.5 | 3.59 | 3.545 | 2570371183 | 2570371141 | |
| 423 | 38 | 1 | 1 | 7 | 16 | 205 | 205 | 5.79 | 5.885 | 5.8375 | 2570371196 | 2570371154 | |
| 424 | 38 | 1 | 3 | 9 | 1 | 1 | 1 | 3.515 | 3.63 | 3.5725 | 2570371401 | 2570371359 | |
| 425 | 38 | 3 | 3 | 9 | 24 | 158 | 158 | 2.305 | 2.415 | 2.3600 | 000000000003 | 2570446292 | 2570446250 |
| 426 | 38 | 1 | 3 | 9 | 24 | 158 | 158 | 3.835 | 3.925 | 3.88 | 2570446300 | 2570446258 | |
| 427 | 38 | 2 | 3 | 9 | 23 | 158 | 158 | 3.14 | 3.215 | 3.1775 | 2570446296 | 2570446254 | |
| 428 | 38 | 2 | 1 | 4 | 9 | 4 | 4 | 2.21 | 2.285 | 2.2475 | 2570447854 | 2570447812 | |
| 429 | 38 | 3 | 3 | 28 | 29 | 254 | 254 | 2.435 | 2.55 | 2.4924999999999997 | 2570468468 | 2570468426 | |
| 430 | 38 | 1 | 2 | 17 | 9 | 40 | 40 | 2.905 | 3.01 | 2.9574999999999996 | 2570476620 | 2570476578 | |
| 431 | 38 | 3 | 2 | 32 | 21 | 166 | 166 | 2.035 | 2.12 | 2.0775 | 2570508025 | 2570507983 | |
| 432 | 38 | 1 | 2 | 32 | 22 | 166 | 166 | 4.56 | 4.655 | 4.6075 | 2570508040 | 2570507998 | |
| 433 | 38 | 2 | 2 | 32 | 21 | 166 | 166 | 5.71 | 5.79 | 5.75 | 2570508046 | 2570508004 | |
| 434 | 38 | 2 | 2 | 31 | 25 | 58 | 58 | 3.12 | 3.21 | 3.165 | 2570536997 | 2570536955 | |

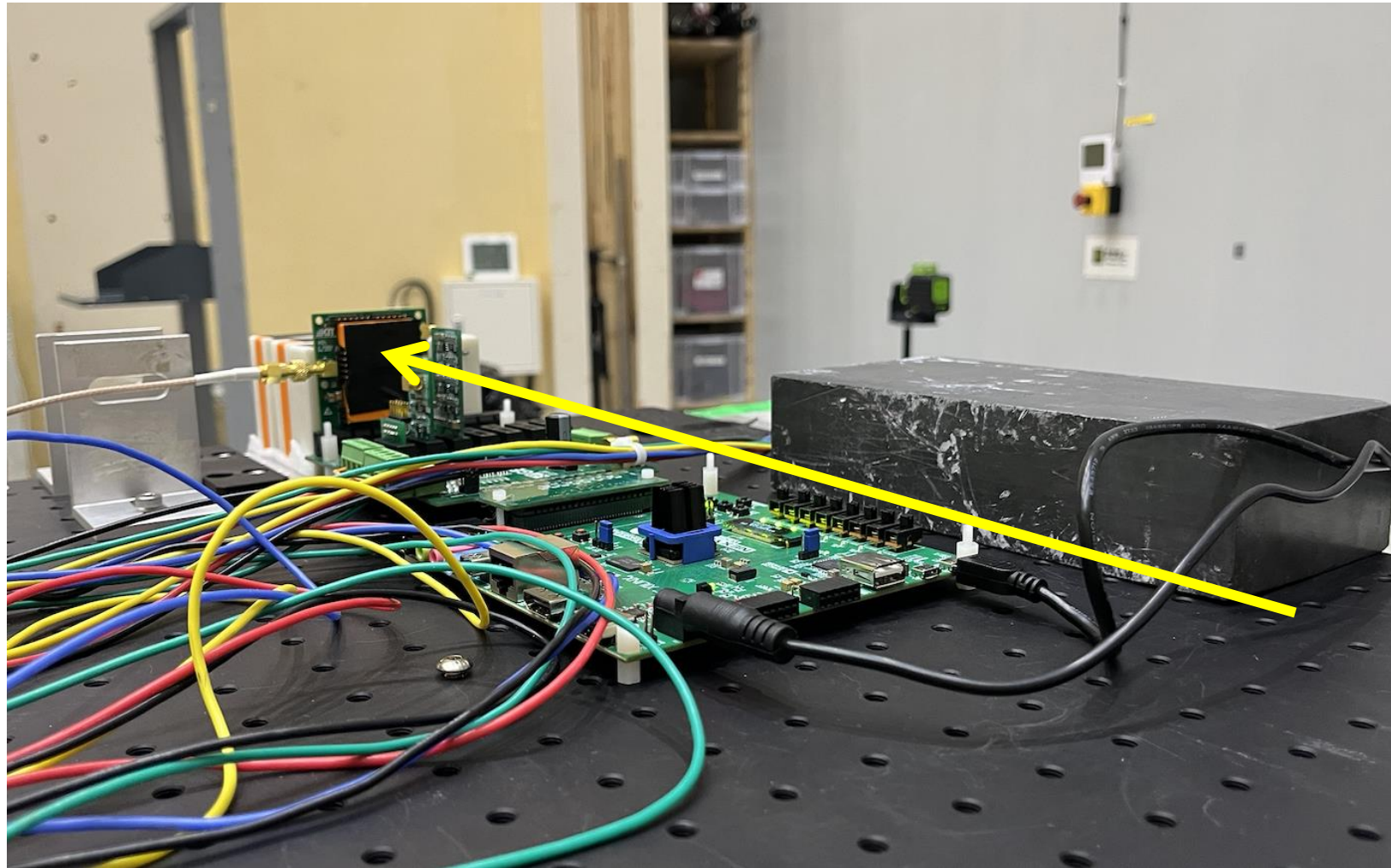
Three v3 Quad chips with W plates: Beam Test Setup

- Three v3 quad-chips stack with 5 mm W plate (= 1 radiation length)
- Confirmed the readout capability limitation of the current setup
- **Two W plate between AstroPix layers**
 - under 5 GeV electron (~ 400 Hz): **Max buffer issue**
- **One W plate between AstroPix layer (1-2 layer/2-3 layer)**
 - 5 GeV electron beam (438 Hz): 1 hour data-taking
 - 1 GeV electron beam (1.1-1.2 kHz): 30 mins data-taking
 - 3 GeV electron beam (1.6-1.7 kHz): **Max buffer issue**



V4 single chip: Beam Test Setup

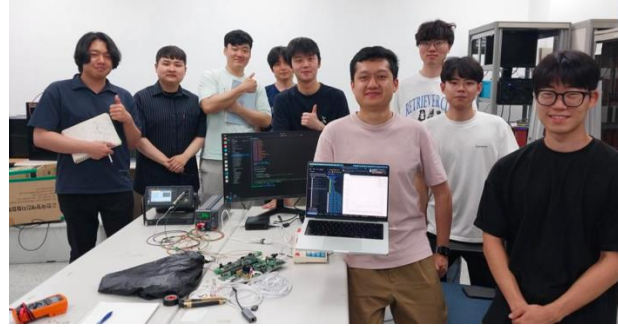
- Setup
 - Used same yml file with Grant
 - Bias voltage: -175 V
 - Threshold: 140 mV
 - Expected data: 1k events per pixel using 3 GeV electron beam
 - Relative calibration
 - Injection curve
 - Am-241/Ba-133 measurement
- Depletion depth study
- Last Friday, v4 chip didn't respond to injection voltages
- Will check it with radiation sources



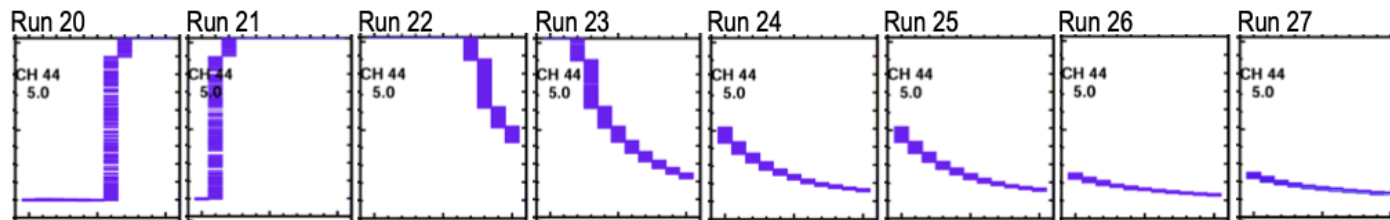
H2GCROC @KNU (from BoGyeong SEO)

2025 June

2025 Dec.



- H2GCROC+KCU105 setup at KNU; same as ANL setup
- SiPM (S14, Hamamatsu; 42 V applied), single channel + SiPM test
 - Using external trigger by function generator for LED power (2V, 20 ns)
 - Run with **different delay** (1 tick = 25 ns)

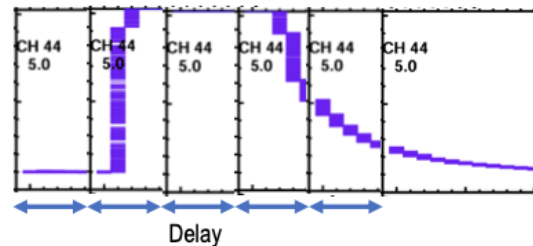


Run with different delay with same signal (same SiPM + LED setup)



- Run with **different delay** (1 tick = 25 ns)
- **Same signal** (same SiPM + LED setup)

Waveform reconstruction



- **New** firmware and UI available from Dec.12, 2025
 - With new firmware and UI, pedestal/ToA/ToT calibration didn't run as expected.



For H2GCROC

- Preamplifier's parameter study
 - to find the best signal-to-noise ratio and a gain adapted to the MIP signal.
 - Using LED as well

114 mitigate the Out-of-Time pileup effect at the shaper output. To meet all these requirements, the gain and
115 the time constant must be adjustable (these parameters are global, not channel-wise). In the table below,
116 all the possibilities are described:

| | | |
|-----------------|------------------------|---|
| Rf (Ω) | 25K, 50K, 66.66K, 100K | In parallel, these resistors provide 15 values to be adjusted with the Cf and Cf_comp values to get a decay time constant around 10 ns. |
| Cf (fF) | 50, 100, 200, 400 | Combined with the Cf_comp capacitors, provide the gain of the preamplifier. |
| Cf_comp (fF) | 100, 200 | Same purpose than Cf capacitors, but connected differently to improve the preamplifier stability. From gain point-of-view can be considered in parallel with Cf capacitors. |

117
118 The following plot shows the preamplifier response to a 10 fC input charge for different choice of gain. The
119 feedback resistor is adjusted so that the $R_f \cdot C_f$ product is constant and so the "duration" of the signal. As can
120 be seen in Fig. 4, an undershoot appears for the highest preamp gain.

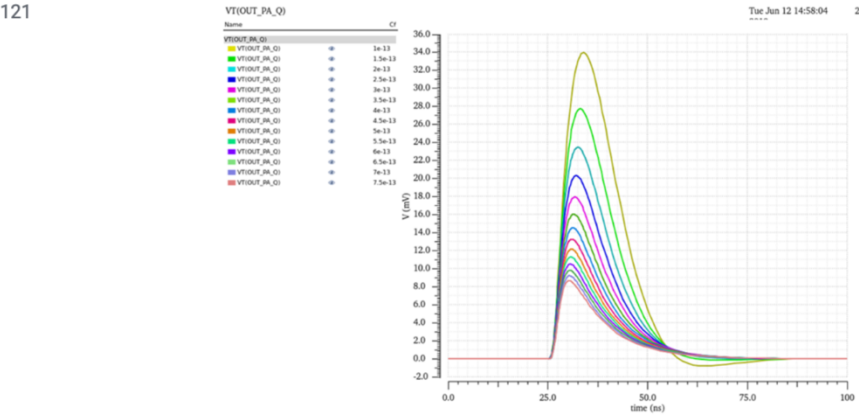
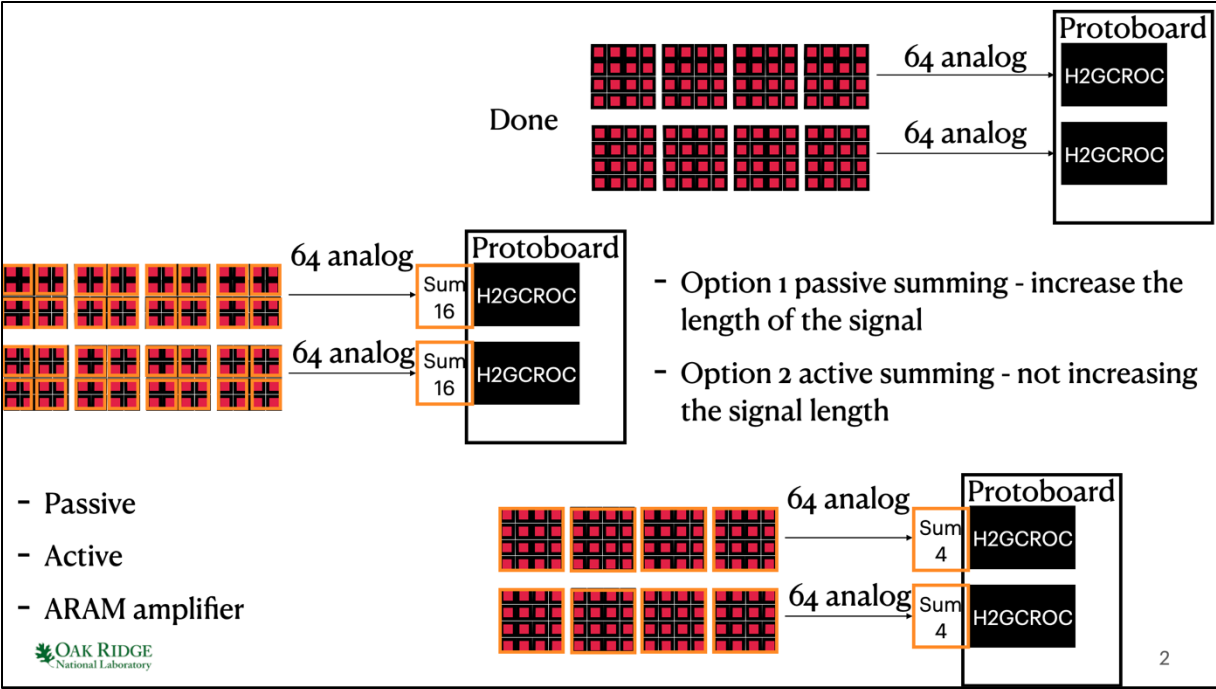


Figure 4 Preamplifier response to a 10 fC input charge for different choice of gain.

- Summing boards skim
 - Consider total channels and available HGCROC
 - Readout
 - 16 channels per one SiPM
 - 4 channels per one SiPM
 - 1 channel per one SiPM



For the upcoming beam test

- Hardware for AstroPix

Available now

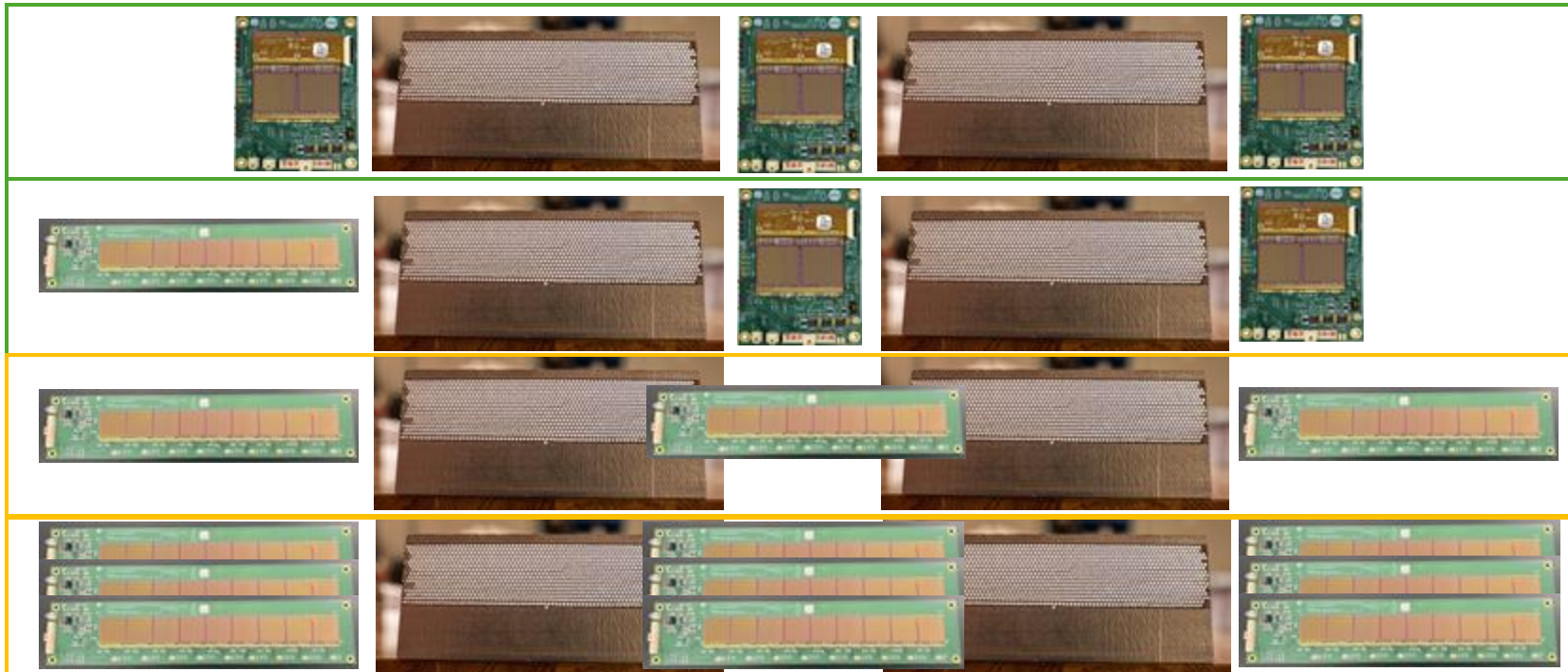
- Three layers of quad chips
- 9-chip + quad + quad
- Three layers of 9-chips
 - Required two more working 9-chip boards
- 3 9-chips + 3 9-chips + 3 9-chips
 - Required eight more working 9-chip boards
 - Required two more A-STEP

- Calorimeter

- One SFIL built by ANL available
- Two SFIL built by U.Regina available
- SiPM boards from Norberts: two boards available at ANL

- Software for AstroPix

- RCDAQ (by Martin)
- Using common external clock (among A-STEPs and H2GCROC); synchronization event using FPGA timestamp



+1 A-STEP

+1 A-STEP

+1 A-STEP

+3 A-STEPs

Depends on
- Available single chips
- Working 9-chip board

Back up